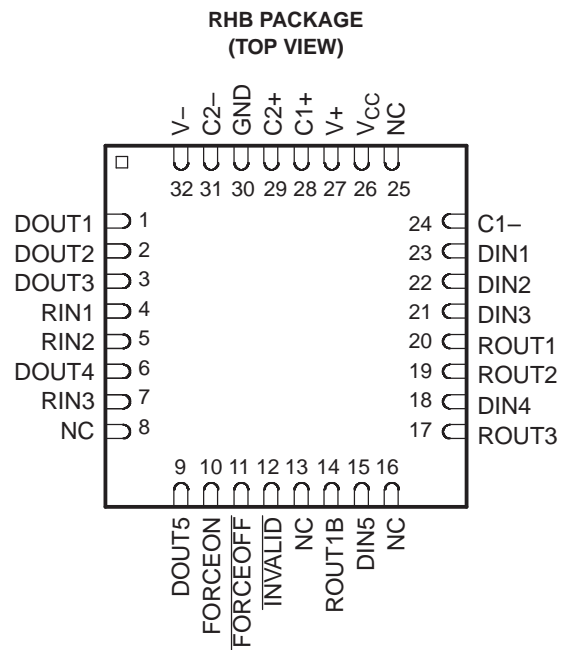
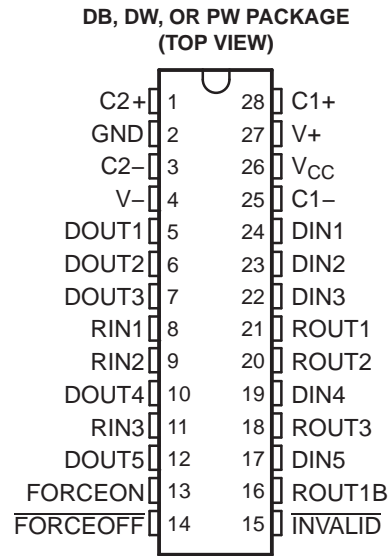


**FEATURES**

- RS-232 Bus-Pin ESD Protection Exceeds  $\pm 15$  kV Using Human-Body Model (HBM)
- Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operate With 3-V to 5.5-V  $V_{CC}$  Supply
- Operate up to 1000 kbit/s
- Five Drivers and Three Receivers
- Auto-Powerdown Plus Feature Enables Flexible Power-Down Mode
- Low Standby Current . . . 1  $\mu$ A Typical
- External Capacitors . . .  $4 \times 0.1 \mu$ F
- Accept 5-V Logic Input With 3.3-V Supply
- Always-Active Noninverting Receiver Output (ROUT1B)
- ESD Protection for RS-232 Interface Pins
  - $\pm 15$  kV – Human-Body Model (HBM)
  - $\pm 8$  kV – IEC61000-4-2, Contact Discharge
  - $\pm 15$  kV – IEC61000-4-2, Air-Gap Discharge

**APPLICATIONS**

- Battery-Powered Systems
- PDAs
- Notebooks
- Subnotebooks
- Laptops
- Palmtop PCs
- Hand-Held Equipment
- Modems
- Printers



**DESCRIPTION/ORDERING INFORMATION**

The SN65C3238E and SN75C3238E consist of five line drivers, three line receivers, and a dual charge-pump circuit with  $\pm 15$ -kV ESD (HBM) protection on the driver output (DOUT) and receiver input (RIN) terminals. The devices meet the requirements of TIA/EIA-232-F and provide the electrical interface between notebook and subnotebook computer applications. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. In addition, the devices include an always-active noninverting output (ROUT1B), which allows applications using the ring indicator to transmit data while the device is powered down. These devices operate at data signaling rates up to 1000 kbit/s.

**PRODUCT PREVIEW**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

**SN65C3238E, SN75C3238E**  
**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS**  
**WITH  $\pm 15$ -kV ESD (HBM) PROTECTION**

SLLS726–MAY 2006

**DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the devices do not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1  $\mu$ A. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus occurs if there is no activity in the logic levels for the driver inputs. Auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the devices activate automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than  $-2.7$  V, or has been between  $-0.3$  V and 0.3 V for less than 30  $\mu$ s. INVALID is low (invalid data) if all receiver input voltages are between  $-0.3$  V and 0.3 V for more than 30  $\mu$ s. Refer to Figure 5 for receiver input levels.

**ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SSOP – DB	Tube of 50	SN75C3238EDB	75C3238E
		Reel of 2000	SN75C3238EDBR	
	TSSOP – PW	Tube of 50	SN75C3238EPW	Preview
		Reel of 2000	SN75C3238EPWR	
	SOIC – DW	Tube of 50	SN75C3238EDW	75C3238E
		Reel of 2000	SN75C3238EDWR	
	QFN – RHB	Reel of 2000	SN75C3238ECRHBR	Preview
	–40°C to 85°C	SSOP – DB	Tube of 50	SN65C3238EDB
Reel of 2000			SN65C3238EDBR	
TSSOP – PW		Tube of 50	SN65C3238EPW	Preview
		Reel of 2000	SN65C3238EPWR	
SOIC – DW		Tube of 50	SN65C3238EDW	65C3238E
		Reel of 2000	SN65C3238EDWR	
QFN – RHB		Reel of 2000	SN65C3238EIRHBR	Preview

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

PRODUCT PREVIEW

**FUNCTION TABLES**

**Each Driver<sup>(1)</sup>**

INPUTS				OUTPUT DOUT	DRIVER STATUS
DIN	FORCEON	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION		
X	X	L	X	Z	Powered off
L	H	H	X	H	Normal operation with auto-powerdown plus disabled
H	H	H	X	L	
L	L	H	<30 s	H	Normal operation with auto-powerdown plus enabled
H	L	H	<30 s	L	
L	L	H	>30 s	Z	Powered off by auto-powerdown plus feature
H	L	H	>30 s	Z	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance

**Each Receiver<sup>(1)</sup>**

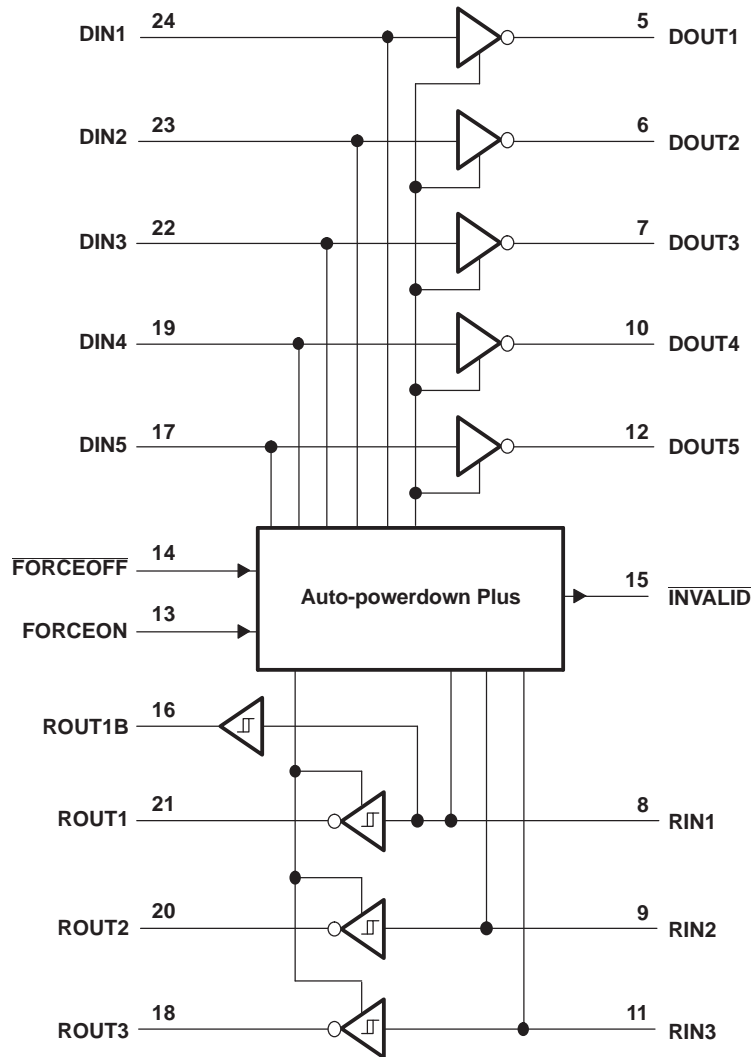
INPUTS				OUTPUTS		RECEIVER STATUS
RIN1	RIN2–RIN3	FORCEOFF	TIME ELAPSED SINCE LAST RIN OR DIN TRANSITION	ROUT1B	ROUT2 AND ROUT3	
L	X	L	X	L	Z	Powered off while ROUT1B is active
H	X	L	X	H	Z	
L	L	H	<30 s	L	H	Normal operation with auto-powerdown plus disabled/enabled
L	H	H	<30 s	L	L	
H	L	H	<30 s	H	H	
H	H	H	<30 s	H	L	
Open	Open	H	<30 s	L	H	

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

**SN65C3238E, SN75C3238E**  
**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS**  
**WITH  $\pm 15$ -kV ESD (HBM) PROTECTION**

SLLS726–MAY 2006

**LOGIC DIAGRAM (POSITIVE LOGIC)**



**PRODUCT PREVIEW**

## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V <sub>CC</sub>	Supply voltage range <sup>(2)</sup>	–0.3	6	V	
V+	Positive-output supply voltage range <sup>(2)</sup>	–0.3	7	V	
V–	Negative-output supply voltage range <sup>(2)</sup>	0.3	–7	V	
V+ – V–	Supply voltage difference <sup>(2)</sup>		13	V	
V <sub>I</sub>	Input voltage range	Driver (FORCEOFF, FORCEON)	–0.3	6	V
		Receiver	–25	25	
V <sub>O</sub>	Output voltage range	Driver	–13.2	13.2	V
		Receiver (INVALID)	–0.3	V <sub>CC</sub> + 0.3	
$\theta_{JA}$	Package thermal impedance <sup>(3)(4)</sup>	DB package		62	°C/W
		DW package		46	
		PW package		62	
		RHB package		TBD	
T <sub>J</sub>	Operating virtual junction temperature		150	°C	
T <sub>stg</sub>	Storage temperature range	–65	150	°C	

- Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- All voltages are with respect to network GND.
- Maximum power dissipation is a function of T<sub>J</sub>(max),  $\theta_{JA}$ , and T<sub>A</sub>. The maximum allowable power dissipation at any allowable ambient temperature is P<sub>D</sub> = (T<sub>J</sub>(max) – T<sub>A</sub>)/ $\theta_{JA}$ . Operating at the absolute maximum T<sub>J</sub> of 150°C can affect reliability.
- The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions<sup>(1)</sup>

See Figure 6

		MIN	NOM	MAX	UNIT
Supply voltage	V <sub>CC</sub> = 3.3 V	3	3.3	3.6	V
	V <sub>CC</sub> = 5 V	4.5	5	5.5	
V <sub>IH</sub> Driver and control high-level input voltage	DIN, FORCEOFF, FORCEON	V <sub>CC</sub> = 3.3 V	2	5.5	V
		V <sub>CC</sub> = 5 V	2.4	5.5	
V <sub>IL</sub> Driver and control low-level input voltage	DIN, FORCEOFF, FORCEON	0		0.8	V
V <sub>I</sub> Receiver input voltage		–25		25	V
T <sub>A</sub> Operating free-air temperature	SN75C3238E	0		70	°C
	SN65C3238E	–40		85	

- Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.

## Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
I <sub>I</sub>	Input leakage current	FORCEOFF, FORCEON		$\pm 0.01$	$\pm 1$	$\mu$ A
I <sub>CC</sub>	Supply current (T <sub>A</sub> = 25°C)	Auto-powerdown plus disabled	No load, FORCEOFF and FORCEON at V <sub>CC</sub>	0.5	2	mA
		Powered off	No load, FORCEOFF at GND	1	10	
		Auto-powerdown plus enabled	No load, FORCEOFF at V <sub>CC</sub> , FORCEON at GND, All RIN are open or grounded	1	10	$\mu$ A

- Testing supply conditions are C1–C4 = 0.1  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.15 V; C1–C4 = 0.22  $\mu$ F at V<sub>CC</sub> = 3.3 V  $\pm$  0.3 V; and C1 = 0.047  $\mu$ F and C2–C4 = 0.33  $\mu$ F at V<sub>CC</sub> = 5 V  $\pm$  0.5 V.
- All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

**SN65C3238E, SN75C3238E**  
**3-V TO 5.5-V MULTICHANNEL RS-232 LINE DRIVERS/RECEIVERS**  
**WITH ±15-kV ESD (HBM) PROTECTION**

SLLS726–MAY 2006

**DRIVER SECTION**

**Electrical Characteristics<sup>(1)</sup>**

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub>	High-level output voltage All DOUT at R <sub>L</sub> = 3 kΩ to GND	5	5.4		V
V <sub>OL</sub>	Low-level output voltage All DOUT at R <sub>L</sub> = 3 kΩ to GND	–5	–5.4		V
I <sub>IH</sub>	High-level input current V <sub>I</sub> = V <sub>CC</sub>		±0.01	±1	μA
I <sub>IL</sub>	Low-level input current V <sub>I</sub> at GND		±0.01	±1	μA
I <sub>OS</sub>	Short-circuit output current <sup>(3)</sup> V <sub>CC</sub> = 3.6 V, V <sub>O</sub> = 0 V		±35	±60	mA
	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 0 V		±40	±100	
r <sub>o</sub>	Output resistance V <sub>CC</sub> , V <sub>+</sub> , and V <sub>–</sub> = 0 V, V <sub>O</sub> = ±2 V	300	10M		Ω
I <sub>OZ</sub>	Output leakage current FORCEOFF = GND			±25	μA
	V <sub>O</sub> = ±12 V, V <sub>CC</sub> = 3 V to 3.6 V			±25	
	V <sub>O</sub> = ±10 V, V <sub>CC</sub> = 4.5 V to 5.5 V			±25	

- (1) Testing supply conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047 μF and C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.
- (2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.
- (3) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

**Switching Characteristics<sup>(1)</sup>**

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
Maximum data rate (see <a href="#">Figure 1</a> )	R <sub>L</sub> = 3 kΩ, One DOUT switching	C <sub>L</sub> = 1000 pF	250		kbit/s
		C <sub>L</sub> = 250 pF, V <sub>CC</sub> = 3 V to 4.5 V	1000		
		C <sub>L</sub> = 1000 pF, V <sub>CC</sub> = 4.5 V to 5.5 V	1000		
t <sub>sk(p)</sub>	Pulse skew <sup>(3)</sup> C <sub>L</sub> = 150 pF to 2500 pF, R <sub>L</sub> = 3 kΩ to 7 kΩ, See <a href="#">Figure 2</a>		25		ns
SR(tr)	Slew rate, transition region (see <a href="#">Figure 1</a> ) C <sub>L</sub> = 150 pF to 1000 pF, R <sub>L</sub> = 3 kΩ to 7 kΩ, V <sub>CC</sub> = 3.3 V		18	150	V/μs

- (1) Testing supply conditions are C1–C4 = 0.1 μF at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22 μF at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047 μF and C2–C4 = 0.33 μF at V<sub>CC</sub> = 5 V ± 0.5 V.
- (2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.
- (3) Pulse skew is defined as |t<sub>PLH</sub> – t<sub>PHL</sub>| of each channel of the same device.

**ESD Protection**

PARAMETER	TEST CONDITIONS	TYP	UNIT
DOUT	HBM	±15	kV
	IEC 61000-4-2, Air-Gap Discharge	±15	
	IEC 61000-4-2, Contact Discharge	±8	

PRODUCT PREVIEW

## RECEIVER SECTION

### Electrical Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 6](#))

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>(2)</sup>	MAX	UNIT
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 0.6	V <sub>CC</sub> - 0.1		V
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 1.6 mA			0.4	V
V <sub>IT+</sub>	Positive-going input threshold voltage	V <sub>CC</sub> = 3.3 V		1.5	2.4	V
		V <sub>CC</sub> = 5 V		1.8	2.4	
V <sub>IT-</sub>	Negative-going input threshold voltage	V <sub>CC</sub> = 3.3 V	0.6	1.2		V
		V <sub>CC</sub> = 5 V	0.8	1.5		
V <sub>hys</sub>	Input hysteresis (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.3		V
I <sub>OZ</sub>	Output leakage current (except ROUT1B)	FORCEOFF = 0 V		±0.05	±10	µA
r <sub>i</sub>	Input resistance	V <sub>i</sub> = ±3 V to ±25 V	3	5	7	kΩ

(1) Testing supply conditions are C1–C4 = 0.1 µF at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

### Switching Characteristics<sup>(1)</sup>

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP <sup>(2)</sup>	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	C <sub>L</sub> = 150 pF, See <a href="#">Figure 3</a>	150	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level output	C <sub>L</sub> = 150 pF, See <a href="#">Figure 3</a>	150	ns
t <sub>en</sub>	Output enable time	C <sub>L</sub> = 150 pF, R <sub>L</sub> = 3 kΩ, See <a href="#">Figure 4</a>	200	ns
t <sub>dis</sub>	Output disable time	C <sub>L</sub> = 150 pF, R <sub>L</sub> = 3 kΩ, See <a href="#">Figure 4</a>	200	ns
t <sub>sk(p)</sub>	Pulse skew <sup>(3)</sup>	See <a href="#">Figure 3</a>	50	ns

(1) Testing supply conditions are C1–C4 = 0.1 µF at V<sub>CC</sub> = 3.3 V ± 0.15 V; C1–C4 = 0.22 µF at V<sub>CC</sub> = 3.3 V ± 0.3 V; and C1 = 0.047 µF and C2–C4 = 0.33 µF at V<sub>CC</sub> = 5 V ± 0.5 V.

(2) All typical values are at V<sub>CC</sub> = 3.3 V or V<sub>CC</sub> = 5 V, and T<sub>A</sub> = 25°C.

(3) Pulse skew is defined as |t<sub>PLH</sub> - t<sub>PHL</sub>| of each channel of the same device.

### ESD Protection

PARAMETER	TEST CONDITIONS	TYP	UNIT
RIN	HBM	±15	kV
	IEC 61000-4-2, Air-Gap Discharge	±15	
	IEC 61000-4-2, Contact Discharge	±8	

## AUTO-POWERDOWN PLUS SECTION

### Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$V_{T+(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, FORCEOFF = $V_{CC}$		2.7	V
$V_{T-(valid)}$	Receiver input threshold for $\overline{INVALID}$ high-level output voltage	FORCEON = GND, FORCEOFF = $V_{CC}$	-2.7		V
$V_{T(invalid)}$	Receiver input threshold for $\overline{INVALID}$ low-level output voltage	FORCEON = GND, FORCEOFF = $V_{CC}$	-0.3	0.3	V
$V_{OH}$	$\overline{INVALID}$ high-level output voltage	$I_{OH} = -1$ mA, FORCEON = GND, FORCEOFF = $V_{CC}$	$V_{CC} - 0.6$		V
$V_{OL}$	$\overline{INVALID}$ low-level output voltage	$I_{OL} = 1.6$ mA, FORCEON = GND, FORCEOFF = $V_{CC}$		0.4	V

### Switching Characteristics

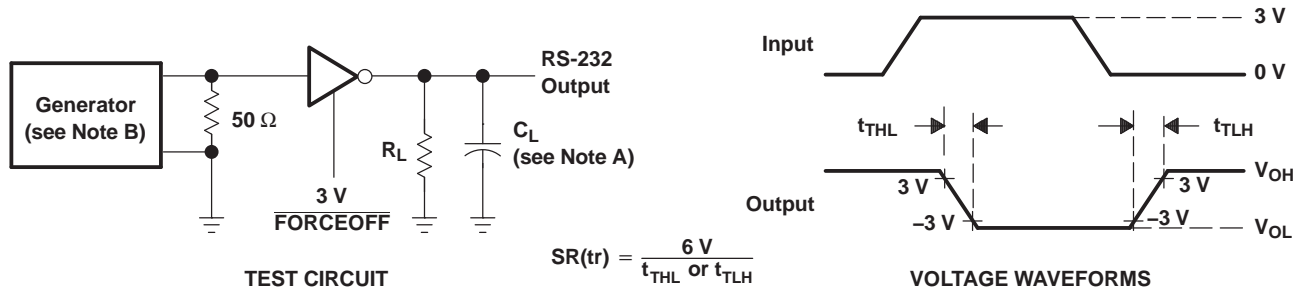
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see [Figure 5](#))

PARAMETER		MIN	TYP <sup>(1)</sup>	MAX	UNIT
$t_{valid}$	Propagation delay time, low- to high-level output		0.1		$\mu$ s
$t_{invalid}$	Propagation delay time, high- to low-level output		50		$\mu$ s
$t_{en}$	Supply enable time		25		$\mu$ s
$t_{dis}$	Receiver or driver edge to auto-powerdown plus	15	30	60	s

(1) All typical values are at  $V_{CC} = 3.3$  V or  $V_{CC} = 5$  V, and  $T_A = 25^\circ\text{C}$ .

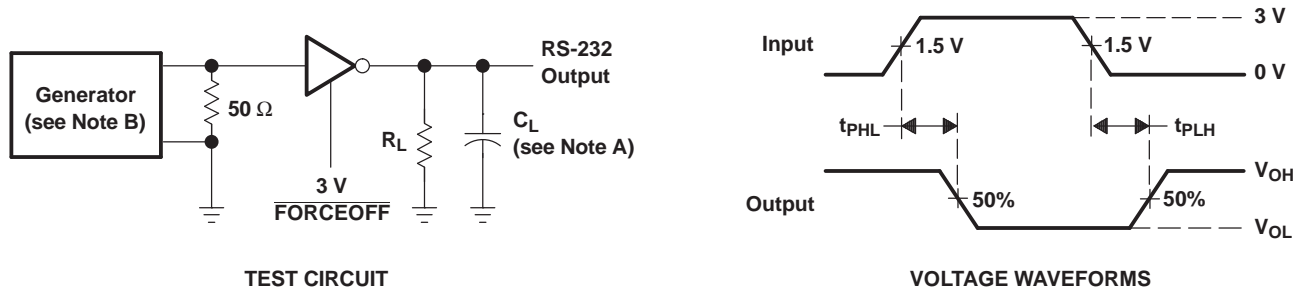


PARAMETER MEASUREMENT INFORMATION



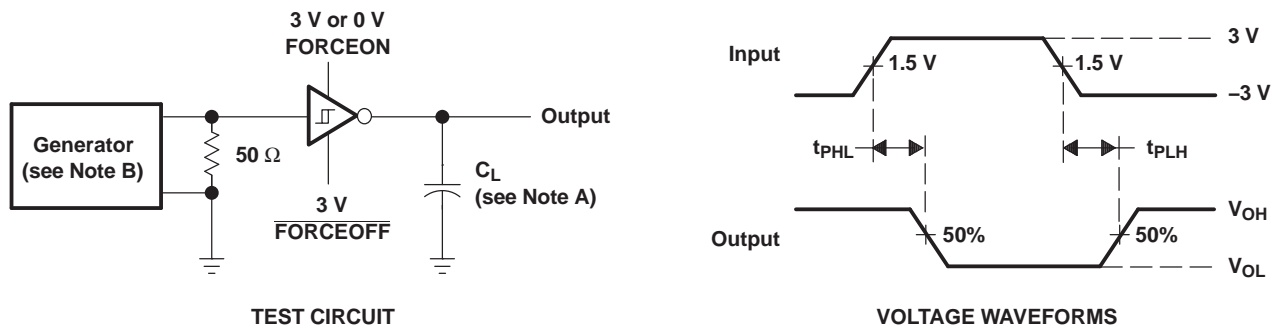
- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10 \text{ ns}$ ,  $t_f \leq 10 \text{ ns}$ .

Figure 1. Driver Slew Rate



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics: PRR = 250 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10 \text{ ns}$ ,  $t_f \leq 10 \text{ ns}$ .

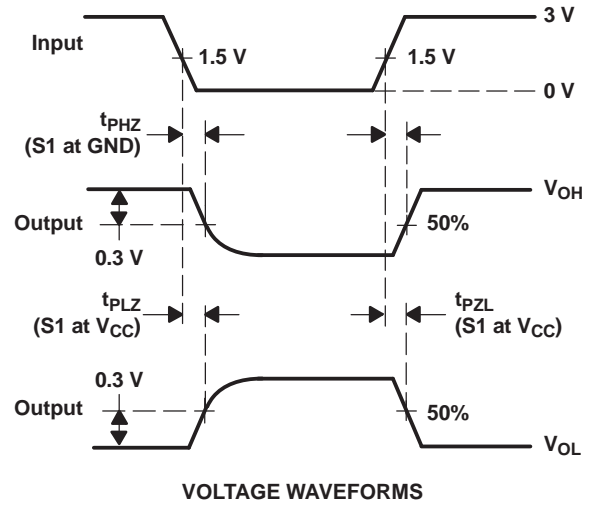
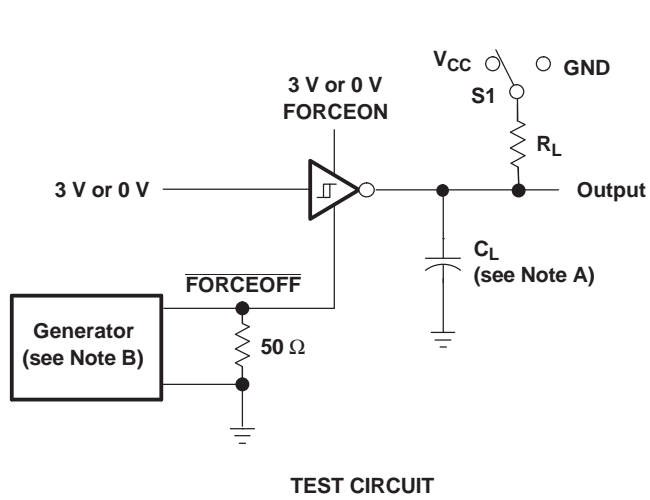
Figure 2. Driver Pulse Skew



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10 \text{ ns}$ ,  $t_f \leq 10 \text{ ns}$ .

Figure 3. Receiver Propagation Delay Times

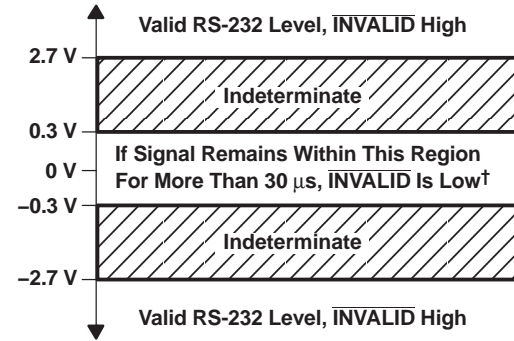
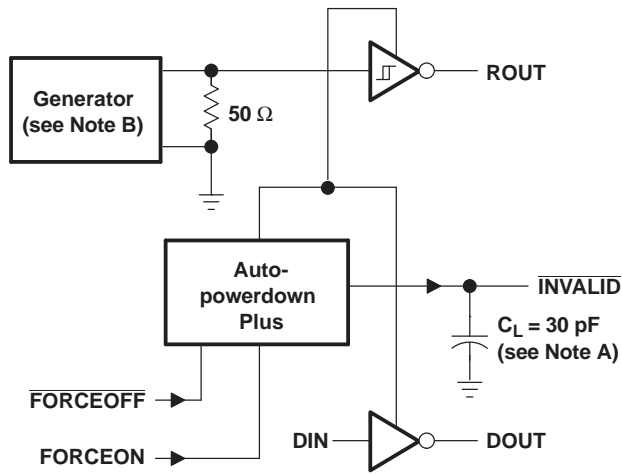
PARAMETER MEASUREMENT INFORMATION (continued)



- A.  $C_L$  includes probe and jig capacitance.
- B. The pulse generator has the following characteristics:  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10 \text{ ns}$ ,  $t_f \leq 10 \text{ ns}$ .
- C.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- D.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .

Figure 4. Receiver Enable and Disable Times

PARAMETER MEASUREMENT INFORMATION (continued)



† Auto-powerdown plus disables drivers and reduces supply current to 1 μA.

TEST CIRCUIT

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. The pulse generator has the following characteristics: PRR = 5 kbit/s,  $Z_O = 50 \Omega$ , 50% duty cycle,  $t_r \leq 10 \text{ ns}$ ,  $t_f \leq 10 \text{ ns}$ .

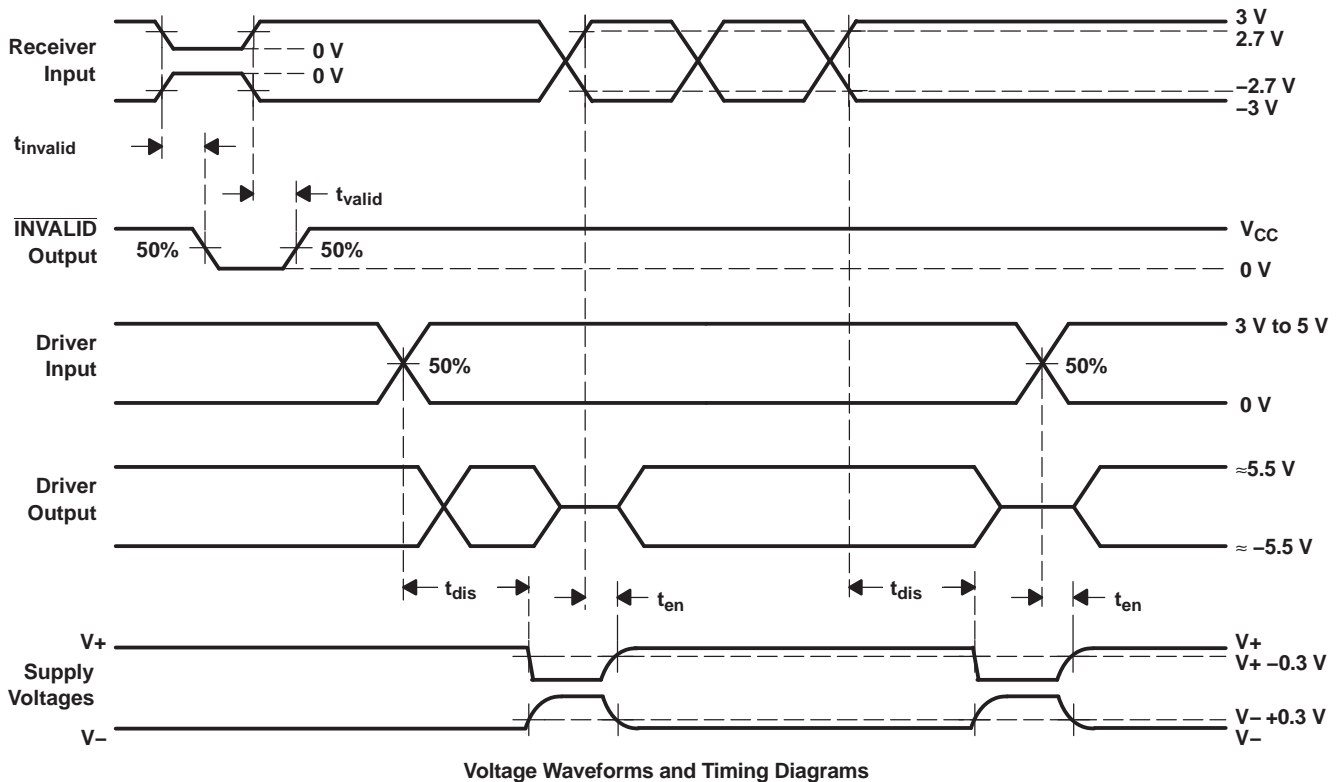
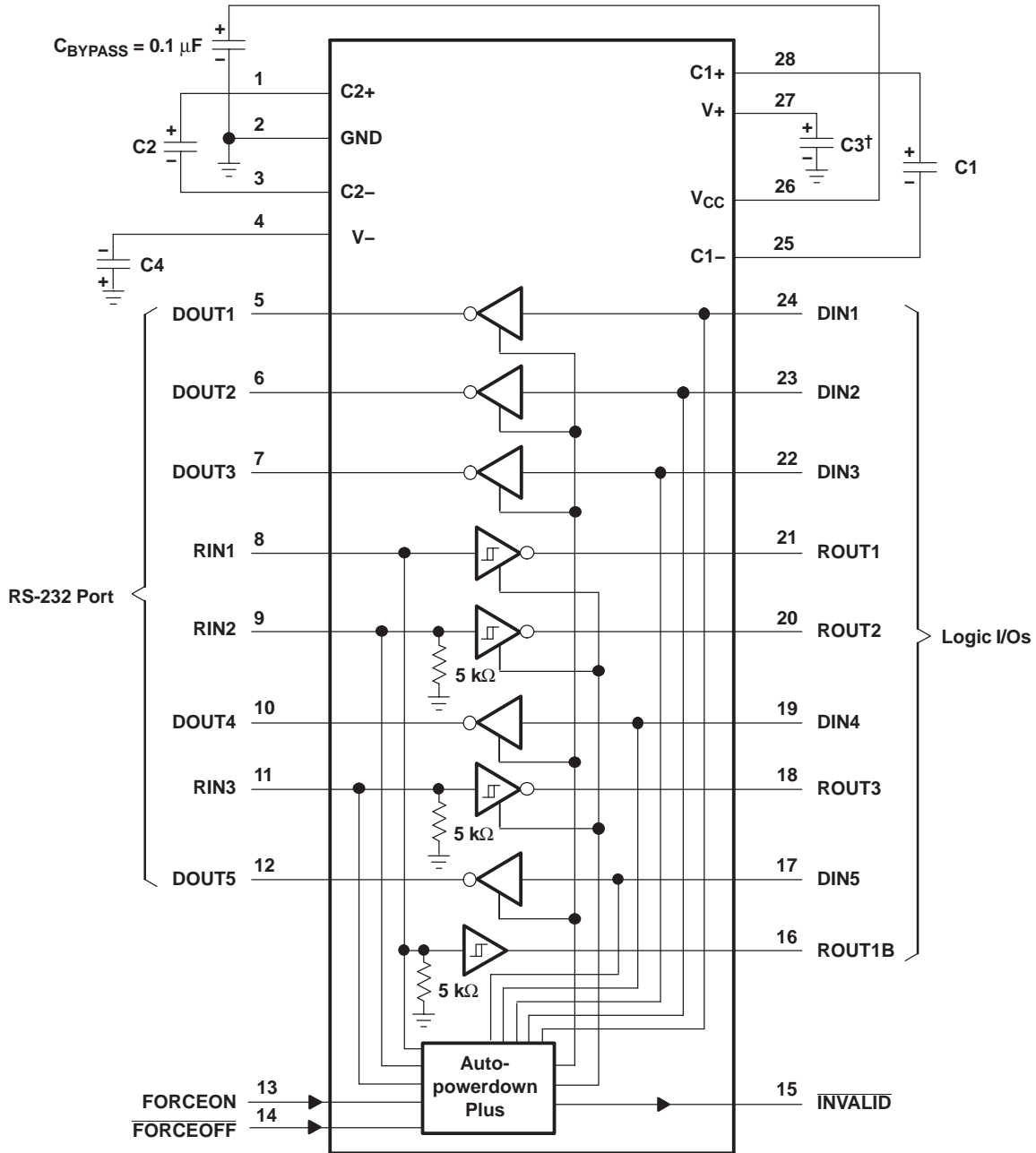


Figure 5.  $\overline{\text{INVALID}}$  Propagation-Delay Times and Supply-Enabling Time

PRODUCT PREVIEW

APPLICATION INFORMATION



V<sub>CC</sub> vs CAPACITOR VALUES

V <sub>CC</sub>	C1	C2, C3, and C4
3.3 V ± 0.15 V	0.1 μF	0.1 μF
3.3 V ± 0.3 V	0.22 μF	0.22 μF
5 V ± 0.5 V	0.047 μF	0.33 μF
3 V to 5.5 V	0.22 μF	1 μF

† C3 can be connected to V<sub>CC</sub> or GND.

NOTES: A. Resistor values shown are nominal.

B. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

Figure 6. Typical Operating Circuit and Capacitor Values

PRODUCT PREVIEW

**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C3238EDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN65C3238EDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
SN75C3238EDBR	SSOP	DB	28	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75C3238EDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

## TAPE AND REEL BOX DIMENSIONS

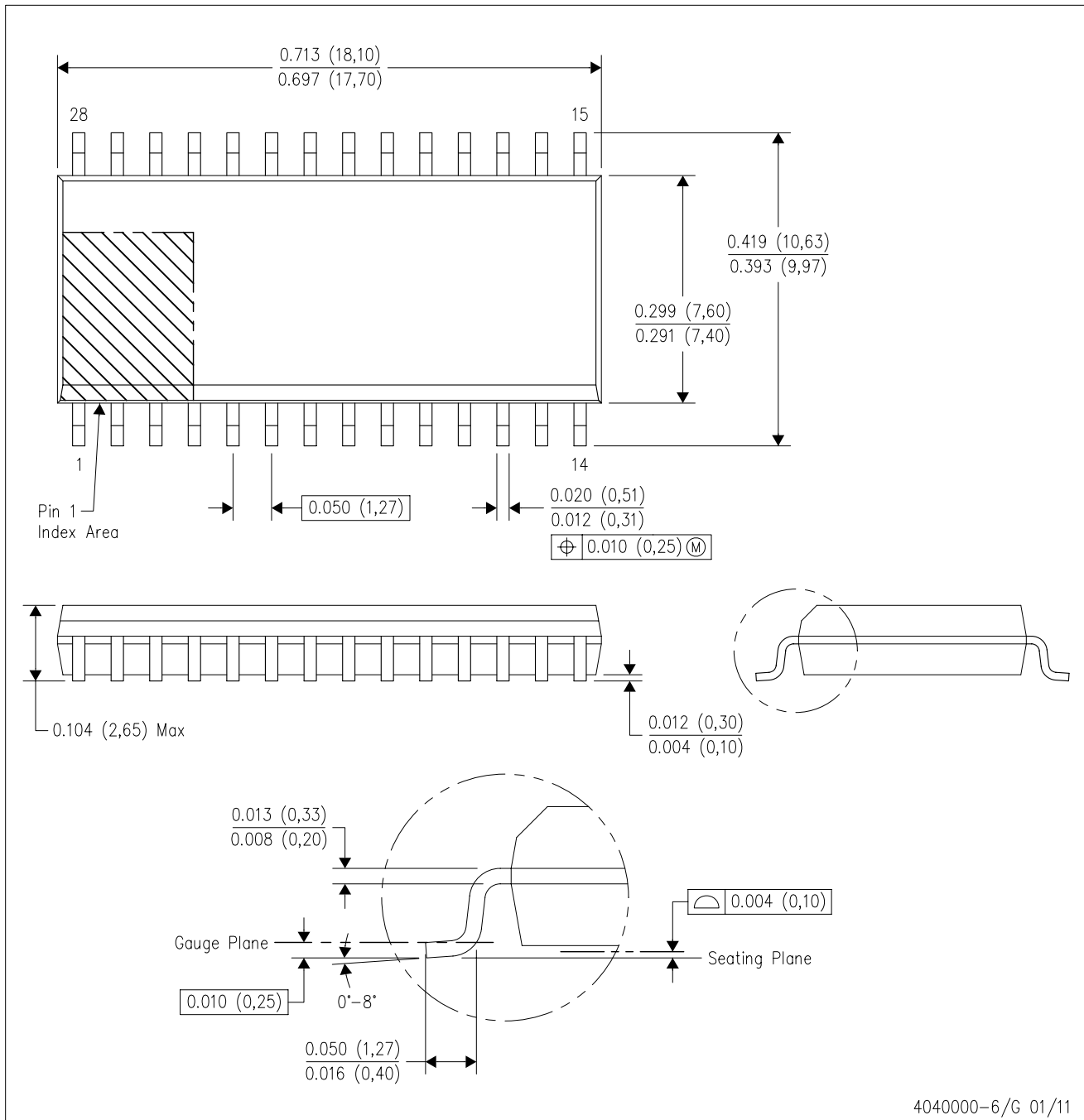


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65C3238EDBR	SSOP	DB	28	2000	367.0	367.0	38.0
SN65C3238EDWR	SOIC	DW	28	1000	367.0	367.0	55.0
SN75C3238EDBR	SSOP	DB	28	2000	367.0	367.0	38.0
SN75C3238EDWR	SOIC	DW	28	1000	367.0	367.0	55.0

DW (R-PDSO-G28)

PLASTIC SMALL OUTLINE

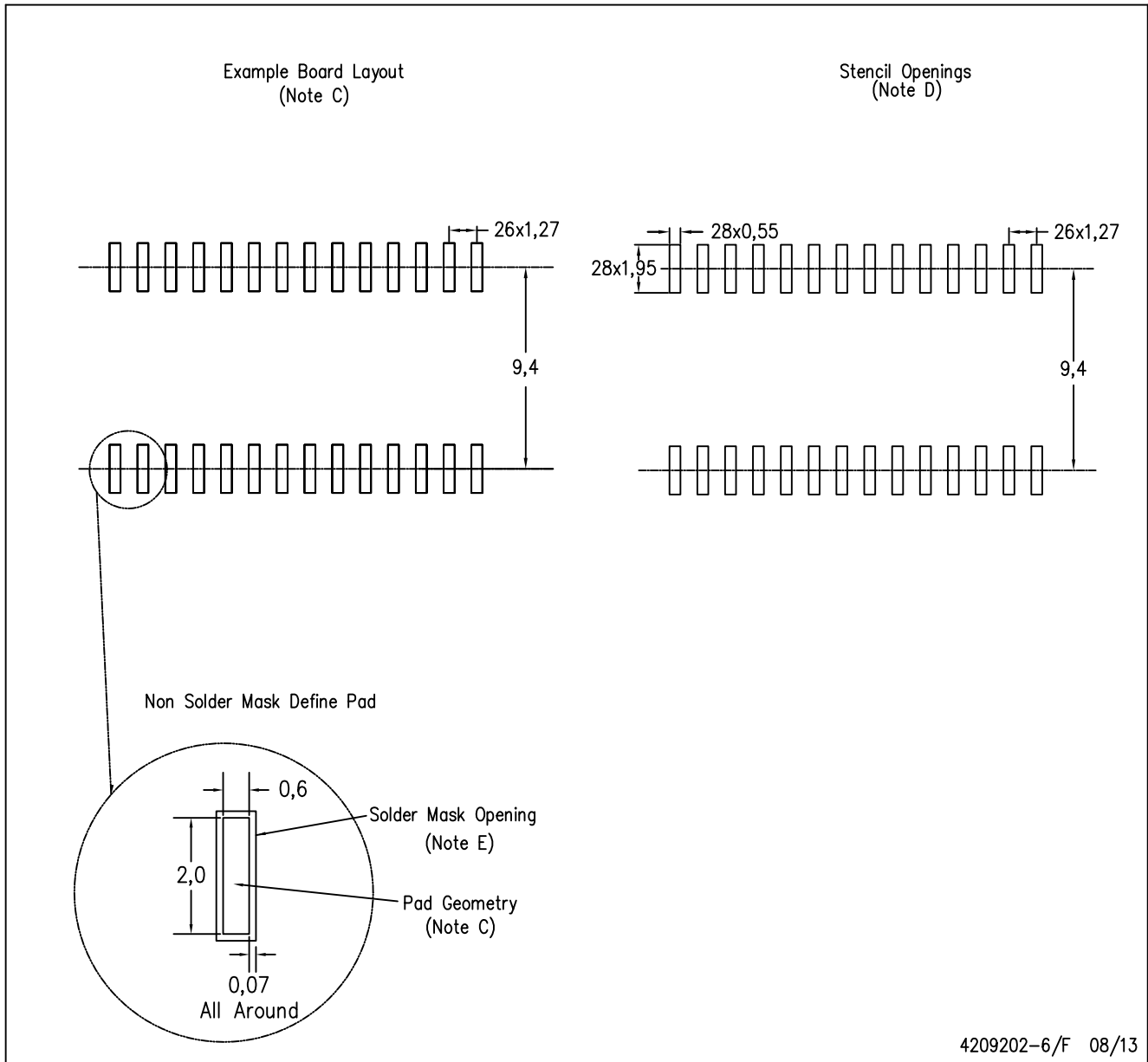


4040000-6/G 01/11

- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AE.

DW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



4209202-6/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)